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Product Information



45µm amber reactive HAF mounting tape

Product Description

tesa HAF® 8430 is a reactive heat activated film based on phenolic resin and nitrile rubber. This amber double sided tape has no backing. It is protected by a strong paper liner and can easily be slit and die cut.

It is activated by heat and pressure applied over a certain period of time.

Product Features

- · Reliable chip module bonding
- · Suitable for PVC, ABS, PET, and PC cards
- · Good workability on all common implanting lines
- · Outstanding ageing resistance
- · Lifelong flexibility due to high rubber content
- At room temperature tesa HAF® 8430 is not tacky.

Application Fields

tesa HAF® 8430 is especially designed for the embedding of chip-modules into smart cards. It is also suitable for bonding of all thermal resistant materials such as metal, glass, plastic, wood and textiles e.g. friction liners for clutches).

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

Product Construction

phenolic resin

Type of liner glassine

Properties/Performance Values

Bonding strength (dynamic 12 N/mm² shear)

Additional Information

Technical recommendations for Smart Card applications:



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Additional Information

tesa HAF® 8430 is not self adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for machine parameters to start with. Please note that optimum parameters strongly depend on the type of machine, particular materials for card bodies and chip modules as well as customer requirements.

1. Pre-lamination:

During pre-lamination, the adhesive tape is laminated onto the module belt. The pre-lamination step does not affect the shelf life time of the adhesive tape. Pre-laminated belts can be stored over the same period of time as the adhesive tape.

Machine setting:

- Temperature 120 140 °C
- Pressure 2 3 bar
- Time 2.5 m/min

2. Module embedding:

During module embedding, the pre-laminated modules are cut from the module belt, positioned into the card cavity and permanently bonded to the card body by heat and pressure. Depending on the type of implanting line, single-step or multiple-step process are possible. Today, most implanting machines have multiple heat press steps.

Single-step process - machine setting:

- Temperature¹ 180 200 °C
- Pressure 65 75 N/module
- Time 1.5 s

Multiple-step process - machine setting:

- Temperature¹ 180 200 °C
- Pressure 65 75 N/module
- Time 2 x 0.7 s / 3 x 0.5 s

PVC and ABS: 180 - 190 °C

PET and PC: 190 - 200 °C

Bonding strength values were obtained under standard laboratory conditions. Value is specification limit checked for each production batch (material: etched aluminum test specimen / bonding conditions: Temp. = 120 °C; pressure = 10 bar; time = 8 min). To reach maximum bonding strength, surfaces should be clean and dry.

¹ Temperature measured inside the heating stamp. Different temperature settings recommended for different card materials:



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